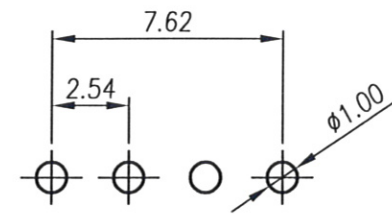
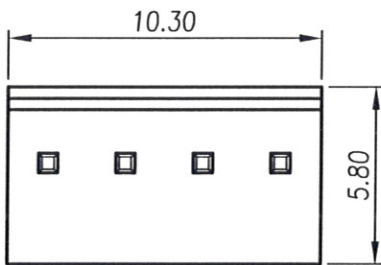


1 2 3 4 5 6 7 8

REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2010.01.19	Ivy
A1	Release To ECN20130303	2013.03.12	Seven
A2	Release To ECN20130812	2013.08.28	Michelle



RECOMMENDED PCB LAYOUT
(TOLERANCE:±0.05)

Specification

- 1.Current Rating:2.5A AC/DC
- 2.Voltage Rating:250V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min. At DC 500V
- 5.Dielectric Withstanding Voltage:AC 800V/Minute
- 6.Operating Temp.:−25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

Finish:

- 1.Housing:See P/N Option
- 2.Contact Pin:See P/N Option

Part No.: AD04900 04 X X 5 2

Number Of Pin
04

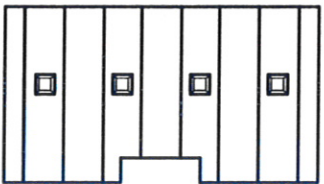
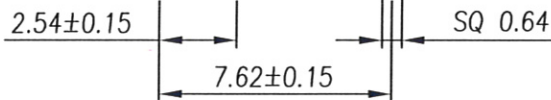
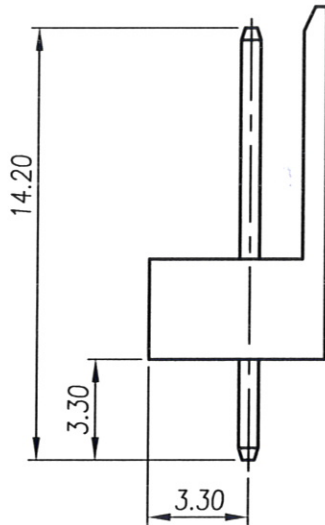
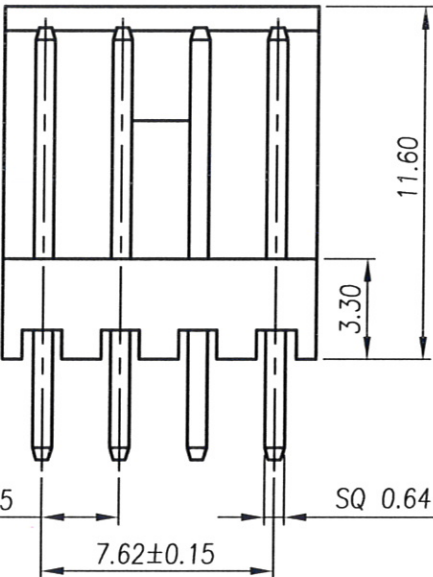
Packing
5:Bag

Housing Material


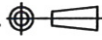
- 1:PA66 UL94V-0 Natural
- 4:PA66+GF UL94V-0 Natural
- N:PA66 UL94V-0 Black

Plating

- 1:Bright Tin Plated Over Nickel
- 2:Matte Tin Plated Over Nickel
- 3:Gold Flash Over Nickel Δ



RoHS Compliant

 金上達科技股份有限公司 GOLDENSUND TECHNOLOGY CO.,LTD		TITLE: Wire To Board Wafer 2.54mm 180° 4P DIP							
		PROJ. 		PART NO. AD0490004XX52		DWG NO. AD0490004XX52			
TOLERANCE UNLESS OTHERWISE SPECIFIED		APR. Jay 20130828		CHK. Seven 20130828		UNITS: mm		CUSTOMER DRAWING	
.x± 0.35 x.'± 2'		DRA. Michelle 20130828		SIZE: A4		SCALE: 4:1		SHEET: 1 / 1	
.xx± 0.25 .x'± 1'		.xxx± 0.15 .xx'± 0.5'		SCALE: 4:1		SHEET: 1 / 1		REV: A2	

1 2 3 4 5 6 7 8

A
B
C
D
E
F

A
B
C
D
E
F